

2294408-2  ACTIVE

TE Internal #: 2294408-2
zSFP+, Cage Assembly, Signal, Operating Temperature Range -40 - 85 °C [-40 - 185 °F], Data Rate (Max) 32 Gb/s, 8 Ports

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Connectors > Pluggable I/O Connectors & Cages > zSFP+ Cage Assembly: EMI Springs



Pluggable I/O Product Type: **Cage Assembly**

Sealable: **No**

Circuit Application: **Signal**

Operating Temperature Range: **-40 - 85 °C [-40 - 185 °F]**

Data Rate (Max): **32 Gb/s**

[All zSFP+ Cage Assembly: EMI Springs \(24\)](#)

Features

Product Type Features

Thermal Accessory Type Included	Heat Sink
Cage Type	Ganged
Pluggable I/O Product Type	Cage Assembly
Sealable	No
Form Factor	zSFP+

Configuration Features

Number of Ports	8
Port Matrix Configuration	1 x 8

Electrical Characteristics

Data Rate (Max)	32 Gb/s
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Body Features

Heat Sink Finish	Electroless Nickel
	.165 in
Heat Sink Height Class	PCI
Heat Sink Style	Pin

Termination Features

Termination Post & Tail Length	2.05 mm[.081 in]
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Termination Method to Printed Circuit Board

Through Hole - Press-Fit

Housing Features

Cage Material

Nickel Silver Alloy

Dimensions

PCB Thickness (Recommended)

2.25 mm [.089 in]

Usage Conditions

Operating Temperature Range

-40 - 85 °C [-40 - 185 °F]

Operation/Application

Heat Sink Compatible

Yes

Circuit Application

Signal

Packaging Features

Packaging Method

Tray

Other

Included Lightpipe

No

EMI Containment Feature Type

Internal/External EMI Springs

Product ComplianceFor compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU

Compliant

EU ELV Directive 2000/53/EC

Compliant

China RoHS 2 Directive MIIT Order No 32, 2016

No Restricted Materials Above Threshold

EU REACH Regulation (EC) No. 1907/2006

Current ECHA Candidate List: JAN 2024 (240)

Candidate List Declared Against: JUL 2021 (219)

Does not contain REACH SVHC

Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

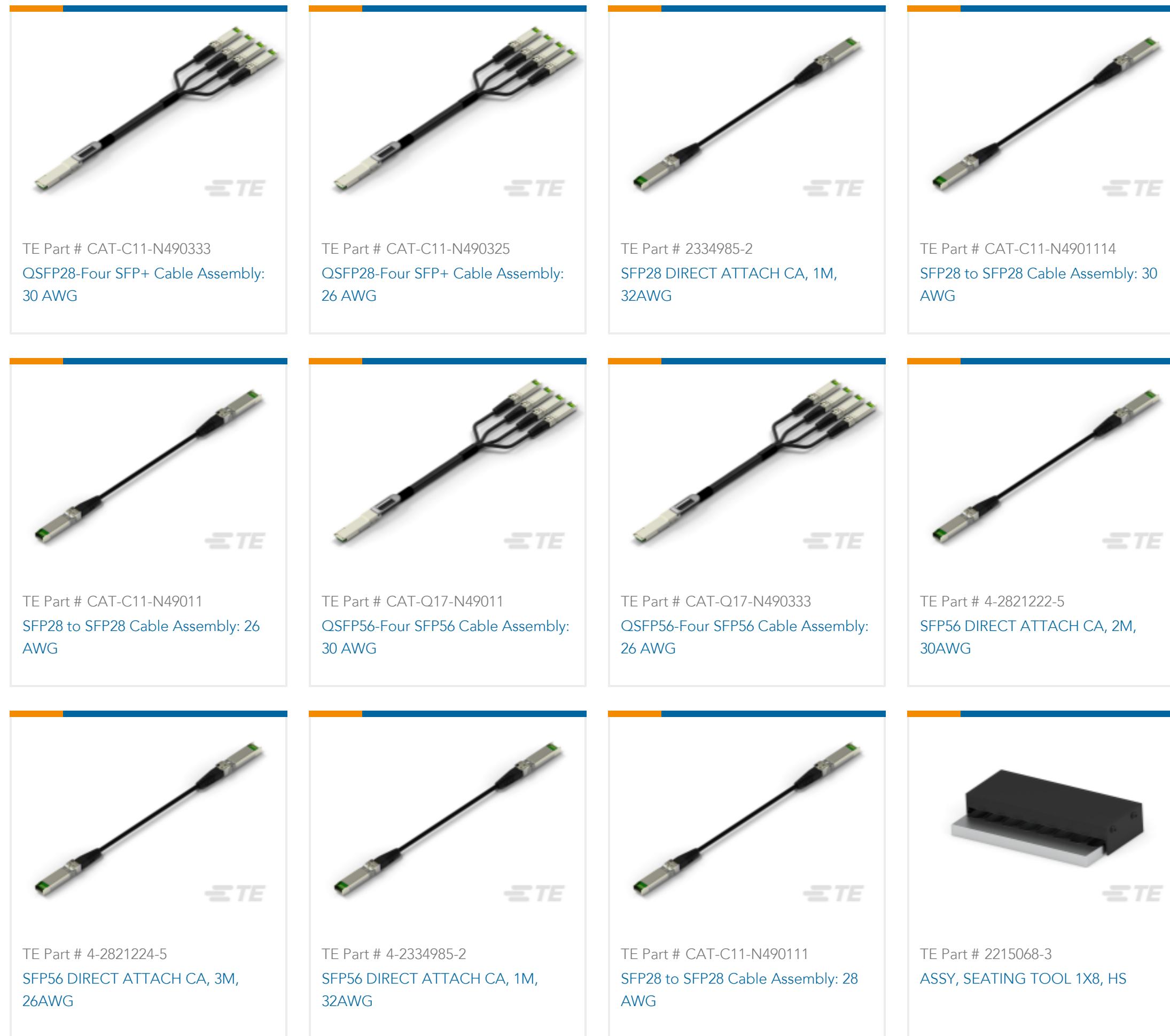
Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products

will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Customers Also Bought





Documents

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_2294408-2_B.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2294408-2_B.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2294408-2_B.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

[zSFP+ Interconnect Brochure](#)

English